Features

- 80C51 Code Compatible
 - 8051 Instruction Compatible
 - 16 I/O + 2 Outputs in 24 Pin Packages
 16 I/O + 6 Outputs in 28 Pin Packages
 - Three 16-bit Timer/Counters
 - 256 Bytes Scratchpad RAM
- Program Memory
 - 8 KB ROM T83C5102
 - 16 KB ROM T83C5101
 - 16 KB EPROM/OTP T87C5101
- High-speed Architecture
- 40 MHz from 2.7 to 5.5V, Commercial or Industrial Temperature Range:
 40 MHz with a 40 MHz Crystal In Std. Mode
 40 MHz with a 20 MHz Crystal In Std. Mode
 - 40 MHz with a 20 MHz Crystal In X2 Mode
- 66 MHz from 4.5 to 5.5V, Commercial Temperature Range
 40 MHz with a 40 MHz Crystal in Std. Mode
 - 66 MHz with a 33 MHz Crystal in X2 Mode
- Dual Data Pointer
- On-chip eXpanded RAM (XRAM) (256 bytes)
- Programmable Clock Out and Up/Down Timer/Counter 2
- Asynchronous Port Reset
- Interrupt Structure with
 - 6 Interrupt Sources,
 - 4-Level Priority Interrupt System
- Full-duplex Enhanced UART
 - Framing Error Detection
 - Automatic Address Recognition
- Low EMI (no ALE)
- Power Control Modes
 - Idle Mode
 - Power-down Mode
- Packages: SO24, DIL24, SSOP24, SO28

Description

The T8xC5101/02 family is a high performance CMOS ROM, OTP, EPROM derivative of the 80C51 CMOS single chip 8-bit microcontroller.

The T8xC5101/02 family is a low pin count device where only Port 1, port 3 and 2/6 bits of a new port 4 are outputted. This prevents any external access, like external program memory access (fetch, MOVC) or external data memory (MOVX). The T8xC5101/02 family retains all features of the 80C51 with extended capacity 8 KB ROM (5102), 16 KB ROM (5101)/16 KB EPROM/OTP (5101), 256 bytes of internal RAM, a 6-source, 4-level interrupt system, an on-chip oscillator and three timer/counters.

In addition, the T8xC5101/02 family has an XRAM of 256 bytes, the X2 feature, a more versatile serial channel that facilitates multiprocessor communication (EUART), a dual data pointer and an improved timer 2. The fully static design of the T8xC5101/02 family allows to reduce system power consumption by bringing the clock frequency down to any value, even DC, without loss of data.

The T8xC5101/02 family has 2 software-selectable modes of reduced activity for further reduction in power consumption. In idle mode the CPU is frozen while the timers, the serial port and the interrupt system are still operating. In power-down mode the RAM is saved and all other functions are inoperative.



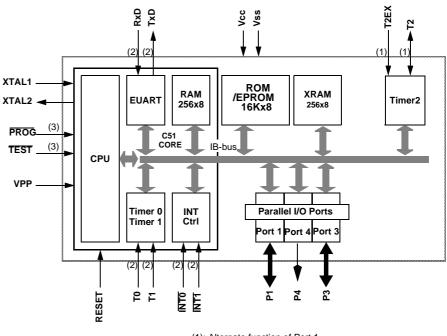


8-bit Low Pin Count Microcontrollers

T83C5101 T87C5101 T83C5102



Block Diagram



(1): Alternate function of Port 1

(2): Alternate function of Port 3(3): Multiplexed function of Port 4.

SFR Mapping The Special I

The Special Function Registers (SFRs) of the T8xC5101/02 fall into the following categories:

- C51 core registers: ACC, B, DPH, DPL, PSW, SP, AUXR1
- I/O port registers: P1, P3, P4
- Timer registers: T2CON, T2MOD, TCON, TH0, TH1, TH2, TMOD, TL0, TL1, TL2, RCAP2L, RCAP2H
- Serial I/O port registers: SADDR, SADEN, SBUF, SCON
- Power and clock control registers: PCON
- Interrupt system registers: IE, IP, IPH
- Others: AUXR, CKCON

No write must be made to reserved areas. Reading a reserved area will give indeterminate results.





Table 1. All SFRs With Their Address and Rest Values

	Bit addressable			No	on Bit addressat	ble			
	0/8	1/9	2/A	3/B	4/C	5/D	6/E	7/F	
F8h									FFh
F0h	B 0000 0000								F7h
E8h									EFh
E0h	ACC 0000 0000								E7h
D8h									DFh
D0h	PSW 0000 0000								D7h
C8h	T2CON 0000 0000	T2MOD XXXX XX00	RCAP2L 0000 0000	RCAP2H 0000 0000	TL2 0000 0000	TH2 0000 0000			CFh
C0h	P4 XX11 1111								C7h
B8h	IP XX00 000	SADEN 0000 0000							BFh
B0h	P3 1111 1111							IPH XX00 0000	B7h
A8h	IE 0X00 0000	SADDR 0000 0000							AFh
A0h			AUXR1 XXXX0XX0						A7h
98h	SCON 0000 0000	SBUF XXXX XXXX							9Fh
90h	P1 1111 1111								97h
88h	TCON 0000 0000	TMOD 0000 0000	TL0 0000 0000	TL1 0000 0000	TH0 0000 0000	TH1 0000 0000	AUXR XXXXXX00	CKCON XXXX XXX0	8Fh
80h		SP 0000 0111	DPL 0000 0000	DPH 0000 0000				PCON 00X1 0000	87h
	0/8	1/9	2/A	3/B	4/C	5/D	6/E	7/F	

Reserved

T8xC5101/02 Pin Configuration

P3.4/T0 1 P3.3/INT1 2 P3.2/INT0 3 P3.1 4 P3.0 5 DIL24 V _{PP} 6 P4.0/Prog 7 SO24 P4.1/Test 8 RST 9 SSOP2 XTAL2 10 XTAL1 11	15 P1.2 14 P1.1/T2EX	P3.4/T0 [1 P3.3/INT1 [2 P3.2/INT0 [3 P3.1 [4 P3.0 [5 V _{PP} [6 P4.3 [7 P4.0/Prog [8 P4.1/Test [9 RST [10 XTAL2 [11	28 Vcc 27 P4.2 26 P3.5/T1 25 P3.6 24 P3.7 23 P1.7 22 P1.6 21 P4.5 20 P1.5 19 P1.4 18 P1.3
Vss [12 * Check for ava	13 P1.0/T2	XTAL2 [] 11 XTAL1 [] 12 P4.4 [] 13 Vss [] 14	17] P1.2 16] P1.1/T2EX 15] P1.0/T2

* Check for availability

	Pin Nu	Pin Number						
Mnemonic	24 pins	28 pins	Туре	Name and Function				
V _{SS}	12	14	I	Ground: 0V reference				
V _{cc}	24	28	I	Power Supply: This is the power supply voltage for normal, idle and power-down operation				
P1.0-P1.7	13-20	15-20 22-23	I/O	Port 1: Port 1 is an 8-bit bidirectional I/O port with internal pull-ups. Port 1 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 1 pins that are externally pulled low will source current because of the internal pull-ups. Port 1				
				also receives the low-order address byte during memory programming and verification. Alternate functions for Port 1 include:				
			I/O	T2 (P1.0): Timer/Counter 2 external count input/Clockout				
			I	T2EX (P1.1): Timer/Counter 2 Reload/Capture/Direction Control				
P4.0 (Prog)-P4.1 (Test)	7 8	8 9	O (I) O (I)	Port 4 bits 0 & 1 : Except during programming and verifying, these two bits are output port driving 30 micro Amps at high level and sinking 10 mA at low level (Vol < $1V$). If they have 1s written to them, they output a high level and if they have 0 written to them, they output a low level. These 2				
				pins cannot be used as inputs. Users should take care to never externally drive these pins low, especially during reset. These two pins are primarily designed to drive LEDs. During programming and verifying, these two pins are used as input, as explained in the corresponding chapter. A Read or a Read/Modify/Write instruction to these bits will read the status of the output: 1 if the				
				output is 1, 0 if the output is 0.				
P4.2-P4.5	NA	27 7 13 21	I/O	Port 4 bits 2 to 5: bidirectional I/O port with internal pull-ups. Port 4.2 to 4.5 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 4.2 to 4.5 pins that are externally pulled low will source current because of the internal pull-ups.				
P3.0-P3.7	5-1 23-21	5-1 26-24	I/O	Port 3: Port 3 is an 8-bit bidirectional I/O port with internal pull-ups. Port 3 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 3 pins that are externally pulled low will source current because of the internal pull-ups. Port 3				
				also serves the special features of the 80C51 family, as listed below.				
	5	5	I	RxD (P3.0): Serial input port				
	4	4	0	TxD (P3.1): Serial output port				
	3	3	I	INTO (P3.2): External interrupt 0				
	2	2	I	INT1 (P3.3): External interrupt 1				





	Pin Nu	Pin Number		
Mnemonic	28 24 pins pins		Туре	Name and Function
	1	1	I	T0 (P3.4): Timer 0 external input
	23	26	I	T1 (P3.5): Timer 1 external input
	22	25	I/O	No alternate function on this pin
	21	24	I/O	No alternate function on this pin
Reset	9	10	I	Reset: A high on this pin for two machine cycles while the oscillator is running, resets the device. An internal diffused resistor to V_{SS} permits a power-on reset using only an external capacitor to V_{CC} .
V _{PP}	6	6	I	Programming Supply Voltage: This pin receives the 12.75V programming supply voltage (V_{PP}) during EPROM programming. During normal operation , V_{PP} pin must be tied to Vcc.
XTAL1	11	12	I	Crystal 1: Input to the inverting oscillator amplifier and input to the internal clock generator circuits.
XTAL2	10	11	0	Crystal 2: Output from the inverting oscillator amplifier

Low Pin Count Specificities

The T8xC5101/02 family is not able to perform any external memory access, such as a code fetch, a look-up table access (using MOVC) or a data access (using MOVX) because traditional Port $\times 0$ and Port 2 are not implemented. It should be noted that 2 bits of a new port 4 are available, but they are pure user outputs. On the 28 pin package, there is also a set of 4 extra I/Os, which cannot be used for external access.

This inability to perform external memory accesses has the following consequences:

- Port 0 SFR doesn't exist
- Port 2 SFR doesn't exist
- Port 4 has six bits defined among which two are pure outputs for LED driving.
- Security level 4 is no longer applicable
- Code memory addresses is limited to 4000h. Accessing to any address above 3FFFh will return indeterminate value. Jumps, subroutine Calls, MOVC instructions should be limited to a maximum address range of 3FFFh to avoid any error.
- External data memory addresses is limited to 100h. Writing to any address above FFh will have no effect. Reading any address above FFh will return indeterminate value. To avoid any mistake, MOVX address should be limited to a maximum address range of FFh.
- In Rx devices, the user could disable the XRAM (for example, if he had shared resource at the corresponding address range). As no external access is possible with the T83/87C510x, it makes no sense to be able to disable accesses to XRAM. Nevertheless, access to AUXR bit 1 will cause no error and any write to this bit will have no effect.
- As there is no external access, EA, ALE, PSEN, RD and WR signals are not implemented. So, the corresponding pins or alternate functions are removed.
- As there is no ALE, there is no need for ALE disabling. Nevertheless, access to AUXR bit 0 will cause no error and any write to this bit will have no effect.
- Compared to the corresponding 16 KB Rx2 device, the TS80C51RB2, the following features are removed:
 - Port 0 & 2
 - PCA
 - Watchdog
 - ONCE mode
 - Power Off Flag (POF)





T8xC5101/02 Enhanced Features

In comparison to the original 80C52, the T8xC5101/02 implements some new features, which are:

- The X2 option.
- The Dual Data Pointer.
- The extended RAM.
- The 4 level interrupt priority system.
- Some enhanced features are also located in the UART and the timer 2.

X2 Feature The T8xC5101/02 core needs only 6 clock periods per machine cycle. This feature called "X2" provides the following advantages:

- Divide frequency crystals by 2 (cheaper crystals) while keeping same CPU power.
- Save power consumption while keeping same CPU power (oscillator power saving).
- Save power consumption by dividing dynamically operating frequency by 2 in operating and idle modes.
- Increase CPU power by 2 while keeping same crystal frequency.

In order to keep the original C51 compatibility, a divider by 2 is inserted between the XTAL1 signal and the main clock input of the core (phase generator). This divider may be disabled by software.

DescriptionThe clock for the whole circuit and peripheral is first divided by two before being used by
the CPU core and peripherals. This allows any cyclic ratio to be accepted on XTAL1
input. In X2 mode, as this divider is bypassed, the signals on XTAL1 must have a cyclic
ratio between 40 to 60%. Figure 1 shows the clock generation block diagram. X2 bit is
validated on XTAL1÷2 rising edge to avoid glitches when switching from X2 to STD
mode. Figure 2 shows the mode switching waveforms.

Figure 1. Clock Generation Diagram

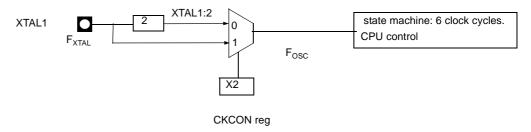
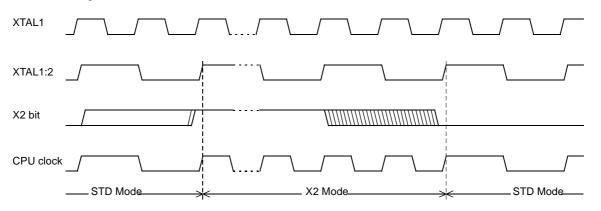


Figure 2. Mode Switching Waveforms



The X2 bit in the CKCON register (See Table 2.) allows to switch from 12 clock cycles per instruction to 6 clock cycles and vice versa. At reset, the standard speed is activated (STD mode). Setting this bit activates the X2 feature (X2 mode).

CAUTION

In order to prevent any incorrect operation while operating in X2 mode, user must be aware that all peripherals using clock frequency as time reference (UART, timers, PCA...) will have their time reference divided by two. For example a free running timer generating an interrupt every 20 ms will then generate an interrupt every 10 ms. UART with 4800 baud rate will have 9600 baud rate.

 Table 2.
 CKCON Register

CKCON - Clock Control Register (8Fh)

7	6	5	4	3	2	1	0					
-	-	-	-	-	-	-	X2					
Bit Number	Bit Mnemonic	Descript	Description									
7	-	Reserved The value	-	is bit is indete	rminate. Do n	ot set this bit.						
6	-	Reserved The value	Reserved The value read from this bit is indeterminate. Do not set this bit.									
5	-		Reserved The value read from this bit is indeterminate. Do not set this bit.									
4	-		Reserved The value read from this bit is indeterminate. Do not set this bit.									
3	-	Reserved The value	-	is bit is indete	rminate. Do n	ot set this bit.						
2	-		Reserved The value read from this bit is indeterminate. Do not set this bit.									
1	-	Reserved The value	-	is bit is indete	rminate. Do n	ot set this bit.						
0	X2	Clear to s F _{OSC} =F _{XT} Set to sel	$\label{eq:cpublic} \begin{array}{l} \textbf{CPU and peripheral clock bit} \\ \text{Clear to select 12 clock periods per machine cycle (STD mode,} \\ \textbf{F}_{\text{OSC}} = \textbf{F}_{\text{XTAL}}/2). \\ \text{Set to select 6 clock periods per machine cycle (X2 mode, } \textbf{F}_{\text{OSC}} = \textbf{F}_{\text{XTAL}}). \end{array}$									

Reset Value = XXXX XXX0b

Not bit addressable



Dual Data Pointer Register (DPTR)

The additional data pointer can be used to speed up code execution and reduce code size in a number of ways.

The dual DPTR structure is a way by which the chip will specify the address of an external data memory location. There are two 16-bit DPTR registers that address the external memory, and a single bit called DPS = AUXR1/bit0 (See Table 3.) that allows the program code to switch between them (Refer to Figure 3).

Figure 3. Use of Dual Pointer

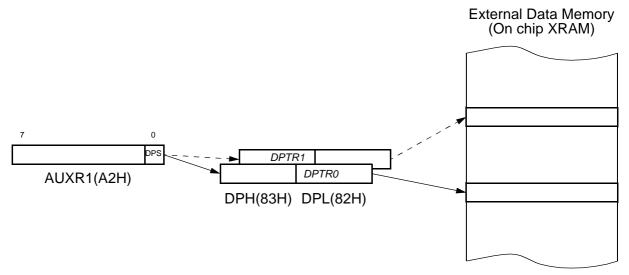


Table 3. AUXR1: Auxiliary Register 1

AUXR1 Address 0A2H		-	-	-	-	GF3	0	-	DPS
	Reset value	Х	Х	Х	Х	0	0	Х	0
Symbol	Function								

Symbol	Function	unction						
-	Not implement	ted, reserved for future use.						
DPS	Data Pointer S	ata Pointer Selection.						
	DPS Operating Mode ⁽¹⁾							
	0	DPTR0 Selected						
	1	1 DPTR1 Selected						
GF3	This bit is a ge	This bit is a general purpose user flag ⁽²⁾						

Notes: 1. User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new feature. In that case, the reset value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate.

2. GF3 will not be available on first version of the RC devices.

Application

Software can take advantage of the additional data pointers to both increase speed and reduce code size, for example, block operations (copy, compare, search ...) are well served by using one data pointer as a 'source' pointer and the other one as a "destination" pointer.

ASSEMBLY LANGUAGE

; Block move using dual data pointers ; Destroys DPTR0, DPTR1, A and PSW ; note: DPS exits opposite of entry state ; unless an extra INC AUXR1 is added 00A2 AUXR1 EQU 0A2H 0000 909000MOV DPTR, #SOURCE ; address of SOURCE 0003 05A2 INC AUXR1 ; switch data pointers 0005 90A000 MOV DPTR,#DEST ; address of DEST 0008 LOOP: 0008 05A2 INC AUXR1 ; switch data pointers 000A E0 MOVX A, @DPTR ; get a byte from SOURCE ; increment SOURCE address 000B A3 INC DPTR 000C 05A2 INC AUXR1 ; switch data pointers ; write the byte to DEST 000E F0 MOVX @DPTR.A 000F A3 INC DPTR ; increment DEST address 0010 70F6JNZ LOOP : check for 0 terminator 0012 05A2 INC AUXR1 ; (optional) restore DPS

INC is a short (2 bytes) and fast (12 clocks) way to manipulate the DPS bit in the AUXR1 SFR. However, note that the INC instruction does not directly force the DPS bit to a particular state, but simply toggles it. In simple routines, such as the block move example, only the fact that DPS is toggled in the proper sequence matters, not its actual value. In other words, the block move routine works the same whether DPS is '0' or '1' on entry. Observe that without the last instruction (INC AUXR1), the routine will exit with DPS in the opposite state.





Expanded RAM (XRAM)

The T8xC5101/02 provide 256 additional Bytes of random access memory (RAM) space for increased data parameter handling and high level language usage.

The T8xC5101/02 have internal data memory that is mapped into four separate segments.

The four segments are:

- 1. The Lower 128 bytes of RAM (addresses 00H to 7FH) are directly and indirectly addressable.
- 2. The Upper 128 bytes of RAM (addresses 80H to FFH) are indirectly addressable only.
- 3. The Special Function Registers, SFRs, (addresses 80H to FFH) are directly addressable only.
- 4. The expanded RAM bytes are indirectly accessed by MOVX instructions.

As external accesses are not possible on the T8xC5101/02 family, it makes no sense to have the possibility to disable accesses to XRAM. That's why, compared to TS80C51RB2, writing a 1 in AUXR register bit 1 will have no effect, and won't disable access to the XRAM.

The Lower 128 bytes can be accessed by either direct or indirect addressing. The Upper 128 bytes can be accessed by indirect addressing only. The Upper 128 bytes occupy the same address space as the SFR. That means they have the same address, but are physically separate from SFR space.

When an instruction accesses an internal location above address 7FH, the CPU knows whether the access is to the upper 128 bytes of data RAM or to SFR space by the addressing mode used in the instruction.

- Instructions that use direct addressing access SFR space. For example: MOV 0A0H, # data, accesses the SFR at location 0B0H (which is P3).
- Instructions that use indirect addressing access the Upper 128 bytes of data RAM.
 For example: MOV @R0, # data where R0 contains 0B0H, accesses the data byte at address 0B0H, rather than P3 (which address is 0B0H).
- The 256 XRAM bytes can be accessed by indirect addressing, with MOVX instructions. This part of memory which is physically located on-chip, logically occupies the first 256 bytes of external data memory.
- The XRAM is indirectly addressed, using the MOVX instruction in combination with any of the registers R0, R1 of the selected bank or DPTR. An access to XRAM will not affect any ports. A write to external data memory locations higher than FFH (i.e. 0100H to FFFFH) will have no effect. A read will return an indeterminate value.

The stack pointer (SP) may be located anywhere in the 256 bytes RAM (lower and upper RAM) internal data memory. The stack may not be located in the XRAM.

T8xC5101/02



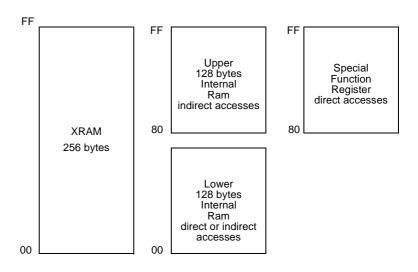


Table 4. Auxiliary Register - AUXR

	AUXR Address 08EH		-	-	-	-	-	EXTRAM	AO			
Reset value		Х	х	х	х	Х	Х	0	0			
Symbol												
-	Not implemented, r	Not implemented, reserved for future use. ⁽¹⁾										
AO	Writing to this bit w	ill have r	o effect	(refer to a	chapter "	Reduced	d EMI mode")					
EXTRAM	Writing to this bit w	ill have r	o effect									

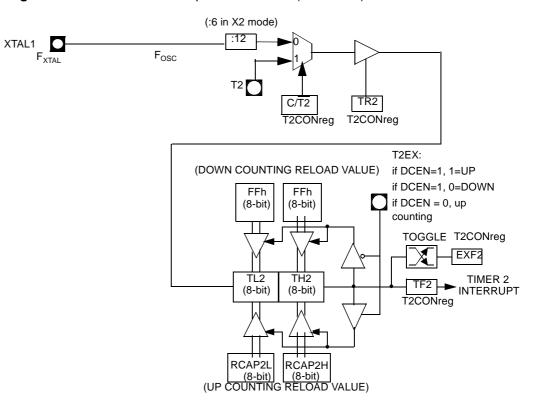
1. User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new features. In that case, the reset or inactive value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate.



	®
Timer 2	The timer 2 in the T8xC5101/02 family is compatible with the timer 2 in the 80C52. It is a 16-bit timer/counter: the count is maintained by two eight-bit timer registers, TH2 and TL2, connected in cascade. It is controlled by T2CON register (See Table 5) and T2MOD register (See Table 6). Timer 2 operation is similar to Timer 0 and Timer 1. C/T2 selects $F_{OSC}/12$ (timer operation) or external pin T2 (counter operation) as the timer clock input. Setting TR2 allows TL2 to be incremented by the selected input.
	Timer 2 has 3 operating modes: capture, autoreload and Baud Rate <u>Generator</u> . These modes are selected by the combination of RCLK, TCLK and CP/RL2 (T2CON), as described in the Atmel 8-bit Microcontroller Hardware description.
	Refer to the Atmel 8-bit Microcontroller Hardware description for the description of Cap- ture and Baud Rate Generator Modes.
	In T8xC5101/02 Timer 2 includes the following enhancements:
	Auto-reload mode with up or down counter
	Programmable clock-output
Auto-Reload Mode	The auto-reload mode configures timer 2 as a 16-bit timer or event counter with auto- matic reload. If DCEN bit in T2MOD is cleared, timer 2 behaves as in 80C52 (refer to the Atmel 8-bit Microcontroller Hardware description). If DCEN bit is set, timer 2 acts as an Up/down timer/counter as shown in Figure 5. In this mode the T2EX pin controls the direction of count.
	When T2EX is high, timer 2 counts up. Timer overflow occurs at FFFFh which sets the TF2 flag and generates an interrupt request. The overflow also causes the 16-bit value in RCAP2H and RCAP2L registers to be loaded into the timer registers TH2 and TL2.
	When T2EX is low, timer 2 counts down. Timer underflow occurs when the count in the timer registers TH2 and TL2 equals the value stored in RCAP2H and RCAP2L registers. The underflow sets TF2 flag and reloads FFFFh into the timer registers.
	The EXF2 bit toggles when timer 2 overflows or underflows according to the the direc-

AMEL

The EXF2 bit toggles when timer 2 overflows or underflows according to the the direction of the count. EXF2 does not generate any interrupt. This bit can be used to provide 17-bit resolution.





Programmable Clock-Output In the clock-out mode, timer 2 operates as a 50%-duty-cycle, programmable clock generator (See Figure 6). The input clock increments TL2 at frequency F_{OSC}/2. The timer repeatedly counts to overflow from a loaded value. At overflow, the contents of RCAP2H and RCAP2L registers are loaded into TH2 and TL2. In this mode, timer 2 overflows do not generate interrupts. The formula gives the clock-out frequency as a function of the system oscillator frequency and the value in the RCAP2H and RCAP2L registers:

$$Clock-OutFrequency = \frac{F_{osc} \times 2^{x^2}}{4 \times (65536 - RCAP2H/RCAP2L)}$$

For a 16 MHz system clock, timer 2 has a programmable frequency range of 61 Hz $(F_{OSC}/2^{16})$ to 4 MHz $(F_{OSC}/4)$ in X1 mode. The generated clock signal is brought out to T2 pin (P1.0).

Timer 2 is programmed for the clock-out mode as follows:

- Set T2OE bit in T2MOD register.
- Clear C/T2 bit in T2CON register.
- Determine the 16-bit reload value from the formula and enter it in RCAP2H/RCAP2L registers.
- Enter a 16-bit initial value in timer registers TH2/TL2. It can be the same as the reload value or a different one depending on the application.
- To start the timer, set TR2 run control bit in T2CON register.





It is possible to use timer 2 as a baud rate generator and a clock generator simultaneously. For this configuration, the baud rates and clock frequencies are not independent since both functions use the values in the RCAP2H and RCAP2L registers.

Figure 6. Clock-Out Mode C/T2 = 0

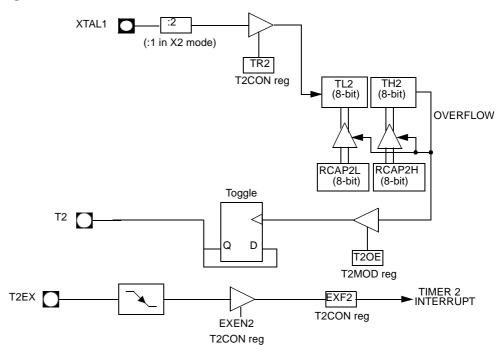


Table 5.T2CON RegisterT2CON - Timer 2 Control Register (C8h)

7	6	5	4	3	2	1	0				
TF2	EXF2	RCLK	TCLK	EXEN2	TR2	C/T2#	CP/RL2#				
Bit Number	Bit Mnemonic	Description									
7	TF2	Must be cleared by	imer 2 overflow Flag lust be cleared by software. et by hardware on timer 2 overflow, if RCLK = 0 and TCLK = 0.								
6	EXF2	Set when a capture When set, causes the	ner 2 External Flag t when a capture or a reload is caused by a negative transition on T2EX pin if EXEN2=1. nen set, causes the CPU to vector to timer 2 interrupt routine when timer 2 interrupt is enabled. Ist be cleared by software. EXF2 doesn't cause an interrupt in Up/down counter mode (DCEN = 1)								
5	RCLK		eceive Clock bit lear to use timer 1 overflow as receive clock for serial port in mode 1 or 3. et to use timer 2 overflow as receive clock for serial port in mode 1 or 3.								
4	TCLK	Clear to use timer 1	Transmit Clock bit Clear to use timer 1 overflow as transmit clock for serial port in mode 1 or 3. Set to use timer 2 overflow as transmit clock for serial port in mode 1 or 3.								
3	EXEN2	Timer 2 External E Clear to ignore ever Set to cause a captu the serial port.	nts on T2EX pin for		on T2EX pin is dete	ected, if timer 2 is r	ot used to clock				
2	TR2	Timer 2 Run contro Clear to turn off time Set to turn on timer	er 2.								
1	C/T2#	Timer/Counter 2 se Clear for timer oper Set for counter oper	ation (input from in	ternal clock system: 2 input pin, falling ec		0 for clock out mo	de.				
0	CP/RL2#	Timer 2 Capture/Re If RCLK=1 or TCLK Clear to auto-reload Set to capture on ne	=1, CP/RL2# is ign on timer 2 overflo	ws or negative trans	itions on T2EX pin if						

Reset Value = 0000 0000b Bit addressable





Table 6. T2MOD Register

T2MOD - Timer 2 Mode Control Register (C9h)

7	6	5	4	3	2	1	0					
-	-	-	-	-	-	T2OE	DCEN					
Bit Number	Bit Mnemonic	Descriptio	Description									
7	-	Reserved The value	Reserved The value read from this bit is indeterminate. Do not set this bit.									
6	-	Reserved The value	Reserved The value read from this bit is indeterminate. Do not set this bit.									
5	-	Reserved The value	Reserved The value read from this bit is indeterminate. Do not set this bit.									
4	-	Reserved The value	Reserved The value read from this bit is indeterminate. Do not set this bit.									
3	-	Reserved The value	read from this	bit is indetern	ninate. Do not	set this bit.						
2	-	Reserved The value	read from this	bit is indetern	ninate. Do not	set this bit.						
1	T2OE	Clear to pro	•	bit 2 as clock inp as clock outpu	•							
0	DCEN	Clear to dis	Down Counter Enable bit Clear to disable timer 2 as up/down counter. Set to enable timer 2 as up/down counter.									

Reset Value = XXXX XX00b Not bit addressable

T8xC5101/02 Serial I/O Port

Framing Error Detection

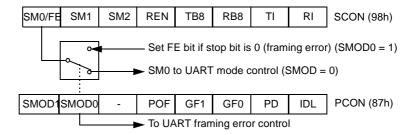
The serial I/O port in the T8xC5101/02 family is compatible with the serial I/O port in the 80C52. It provides both synchronous and asynchronous communication modes. It operates as an Universal Asynchronous Receiver and Transmitter (UART) in three fullduplex modes (Modes 1, 2 and 3). Asynchronous transmission and reception can occur simultaneously and at different baud rates.

Serial I/O port includes the following enhancements:

- Framing error detection
- Automatic address recognition

Framing bit error detection is provided for the three asynchronous modes (modes 1, 2 and 3). To enable the framing bit error detection feature, set SMOD0 bit in PCON register (See Figure 7).

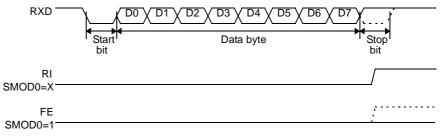
Figure 7. Framing Error Block Diagram



When this feature is enabled, the receiver checks each incoming data frame for a valid stop bit. An invalid stop bit may result from noise on the serial lines or from simultaneous transmission by two CPUs. If a valid stop bit is not found, the Framing Error bit (FE) in SCON register (See) bit is set.

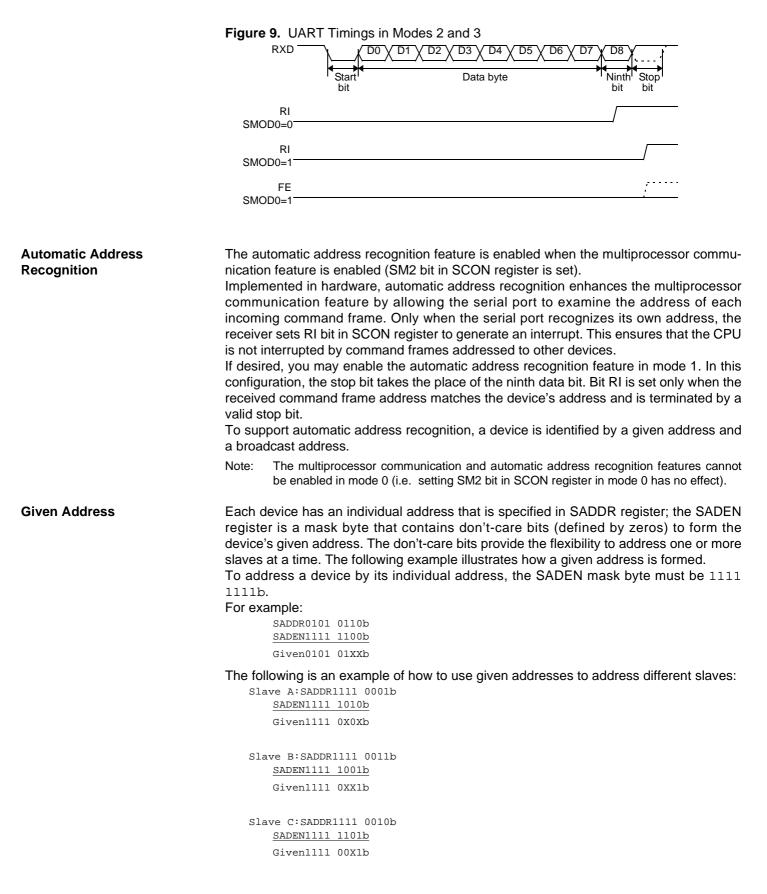
Software may examine FE bit after each reception to check for data errors. Once set, only software or a reset can clear FE bit. Subsequently received frames with valid stop bits cannot clear FE bit. When FE feature is enabled, RI rises on stop bit instead of the last data bit (See Figure 8. and Figure 9.).











The SADEN byte is selected so that each slave may be addressed separately. For slave A, bit 0 (the LSB) is a don't-care bit; for slaves B and C, bit 0 is a 1. To communicate with slave A only, the master must send an address where bit 0 is clear (e.g. 1111 0000b).

For slave A, bit 1 is a 1; for slaves B and C, bit 1 is a don't care bit. To communicate with slaves B and C, but not slave A, the master must send an address with bits 0 and 1 both set (e.g. 1111 0011b).

To communicate with slaves A, B and C, the master must send an address with bit 0 set, bit 1 clear, and bit 2 clear (e.g. 1111 0001b).

Broadcast Address A broadcast address is formed from the logical OR of the SADDR and SADEN registers with zeros defined as don't-care bits, e.g.:

SADDR 0101 0110b SADEN 1111 1100b Broadcast =SADDR OR SADEN1111 111Xb

The use of don't-care bits provides flexibility in defining the broadcast address, however in most applications, a broadcast address is FFh. The following is an example of using broadcast addresses:

Slave A:SADDR1111 0001b <u>SADEN1111 1010b</u> Broadcast1111 1X11b, Slave B:SADDR1111 0011b <u>SADEN1111 1001b</u> Broadcast1111 1X11B, Slave C:SADDR=1111 0010b <u>SADEN1111 1101b</u> Broadcast1111 1111b

For slaves A and B, bit 2 is a don't care bit; for slave C, bit 2 is set. To communicate with all of the slaves, the master must send an address FFh. To communicate with slaves A and B, but not slave C, the master can send and address FBh.

Reset AddressesOn reset, the SADDR and SADEN registers are initialized to 00h, i.e. the given and
broadcast addresses are XXXX XXXb (all don't-care bits). This ensures that the serial
port will reply to any address, and so, that it is backwards compatible with the 80C51
microcontrollers that do not support automatic address recognition.





Table 7. SADEN RegisterSADEN - Slave Address Mask Register (B9h)

7	6	5	4	3	2	1	0

Reset Value = 0000 0000b Not bit addressable

Table 8. SAADR Register SADDR Slave Address Register

SADDR - Slave Address Register (A9h)

7	6	5	4	3	2	1	0

Reset Value = 0000 0000b

Not bit addressable

Table 9. SCON RegisterSCON - Serial Control Register (98h)

7	6	5	4	3	2	1	0	
FE/SM0	SM1	SM2	REN	TB8	RB8	TI	RI	
Bit Number	Bit Mnemonic	Description						
7	FE	Clear to reset Set by hardwa	Framing Error bit (SMOD0=1) Clear to reset the error state, not cleared by a valid stop bit. Set by hardware when an invalid stop bit is detected. SMOD0 must be set to enable access to the FE bit					
	SMO	Refer to SM1 f	erial port Mode bit 0 efer to SM1 for serial port mode selection. MOD0 must be cleared to enable access to the SM0 bit					
6	SM1	<u>SM0 SM1 Mod</u> 0 0 0 1 1 0	1 1 8-bit UART Variable 0 2 9-bit UART $F_{XTAL}/64$ or $F_{XTAL}/32$ (/32, /16in X2 mode)					
5	SM2	Clear to disable Set to enable r	Serial port Mode 2 bit/Multiprocessor Communication Enable bit Clear to disable multiprocessor communication feature. Set to enable multiprocessor communication feature in mode 2 and 3, and eventually mode 1. This bit should be cleared in mode 0.					
4	REN		able bit le serial reception. serial reception.					
3	TB8	Clear to transr	Transmitter Bit 8/Ninth bit to transmit in modes 2 and 3. Clear to transmit a logic 0 in the 9th bit. Set to transmit a logic 1 in the 9th bit.					
2	RB8	Cleared by ha Set by hardwa	Receiver Bit 8/Ninth bit received in modes 2 and 3 Cleared by hardware if 9th bit received is a logic 0. Set by hardware if 9th bit received is a logic 1. In mode 1, if SM2 = 0, RB8 is the received stop bit. In mode 0 RB8 is not used.					
1	ті	Clear to ackno	Fransmit Interrupt flag Clear to acknowledge interrupt. Set by hardware at the end of the 8th bit time in mode 0 or at the beginning of the stop bit in the other					
0	RI	Clear to ackno	Receive Interrupt flag Clear to acknowledge interrupt. Set by hardware at the end of the 8th bit time in mode 0, see Figure 8. and Figure 9. in the other modes.					

Reset Value = 0000 0000b Bit addressable





Table 10. PCON Register

PCON - Power Control Register (87h)

7	6	5	4	3	2	1	0		
SMOD1	SMOD0	-	POF	GF1	GF0	PD	IDL		
Bit Number	Bit Mnemoni	ic Descrip	otion						
7	SMOD1		Serial port Mode bit 1 Set to select double baud rate in mode 1, 2 or 3.						
6	SMODO	Clear to	Serial port Mode bit 0 Clear to select SM0 bit in SCON register. Set to to select FE bit in SCON register.						
5	- Reserved The value read from this bit is inc				erminate. Do not set this bit.				
4	POF	Clear to Set by h	Power-Off Flag Clear to recognize next reset type. Set by hardware when VCC rises from 0 to its nominal voltage. Can also b set by software.						
3	GF1	Cleared	General purpose Flag Cleared by user for general purpose usage. Set by user for general purpose usage.						
2	GF0	Cleared	General purpose Flag Cleared by user for general purpose usage. Set by user for general purpose usage.						
1	PD	Cleared	Power-Down mode bit Cleared by hardware when reset occurs. Set to enter power-down mode.						
0	IDL	-			r reset occurs				

Reset Value = 00X1 0000b Not bit addressable

Power-off flag reset value will be 1 only after a power on (cold reset). A warm reset doesn't affect the value of this bit.

Interrupt System

The T8xC5101/02 family has a total of 6 interrupt vectors: two external interrupts ($\overline{INT0}$ and $\overline{INT1}$), three timer interrupts (timers 0, 1 and 2) and the serial port interrupt. These interrupts are shown in Figure 10. The addresses of the interrupt vectors are the same as in the standard C52.

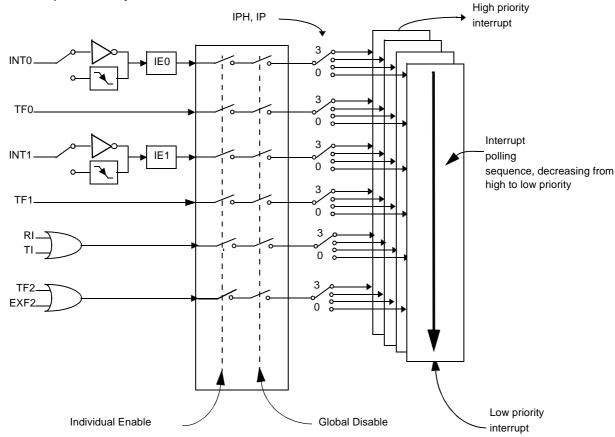


Figure 10. Interrupt Control System

Each of the interrupt sources can be individually enabled or disabled by setting or clearing a bit in the Interrupt Enable register (See Table 12). This register also contains a global disable bit, which must be cleared to disable all interrupts at once.

Each interrupt source can also be individually programmed to one out of four priority levels by setting or clearing a bit in the Interrupt Priority register (See Table 13) and in the Interrupt Priority High register (See Table 14). shows the bit values and priority levels associated with each combination.

IPH.x	IP.x	Interrupt Level Priority
0	0	0 (Lowest)
0	1	1
1	0	2
1	1	3 (Highest)

 Table 11.
 Priority Level Bit Values





A low-priority interrupt can be interrupted by a high priority interrupt, but not by another low-priority interrupt. A high-priority interrupt can't be interrupted by any other interrupt source.

If two interrupt requests of different priority levels are received simultaneously, the request of higher priority level is serviced. If interrupt requests of the same priority level are received simultaneously, an internal polling sequence determines which request is serviced. Thus within each priority level there is a second priority structure determined by the polling sequence.

Table 12. IE Register

IE - Interrupt Enable Register (A8h)

7	6	5	4	3	2	1	0	
EA	-	ET2	ES	ET1	EX1	ET0	EX0	
Bit Number	Bit Mnemonic	Description						
7	EA	Clear to disa Set to enable If EA=1, eac	inable All interrupt bit Clear to disable all interrupts. Set to enable all interrupts. EA=1, each interrupt source is individually enabled or disabled by setting or learing its own interrupt enable bit.					
6	-	Reserved The value re	Reserved The value read from this bit is indeterminate. Do not set this bit.					
5	ET2	Clear to disa	Timer 2 overflow interrupt Enable bit Clear to disable timer 2 overflow interrupt. Set to enable timer 2 overflow interrupt.					
4	ES		Enable bit ble serial por e serial port ir					
3	ET1	Clear to disa	ble timer 1 ov	pt Enable bit verflow interrup flow interrupt.	ot.			
2	EX1	Clear to disa	External interrupt 1 Enable bit Clear to disable external interrupt 1. Set to enable external interrupt 1.					
1	ET0	Clear to disa	Timer 0 overflow interrupt Enable bit Clear to disable timer 0 overflow interrupt. Set to enable timer 0 overflow interrupt.					
0	EX0	Clear to disa	External interrupt 0 Enable bit Clear to disable external interrupt 0. Set to enable external interrupt 0.					

Reset Value = 0X00 0000b Bit addressable

Table 13. IP RegisterIP - Interrupt Priority Register (B8h)

7	6	5	4	3	2	1	0	
-	-	PT2	PS	PT1	PX1	PT0	PX0	
Bit Number	Bit Mnemonic	Description	Description					
7	-	Reserved The value re	Reserved The value read from this bit is indeterminate. Do not set this bit.					
6	-	Reserved The value re	Reserved The value read from this bit is indeterminate. Do not set this bit.					
5	PT2		Timer 2 overflow interrupt Priority bit Refer to PT2H for priority level.					
4	PS		Serial port Priority bit Refer to PSH for priority level.					
3	PT1		rflow interru H for priority	pt Priority bit level.				
2	PX1		External interrupt 1 Priority bit Refer to PX1H for priority level.					
1	PT0		Timer 0 overflow interrupt Priority bit Refer to PT0H for priority level.					
0	PX0		errupt 0 Prio)H for priority					

Reset Value = XX00 0000b Bit addressable



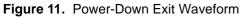


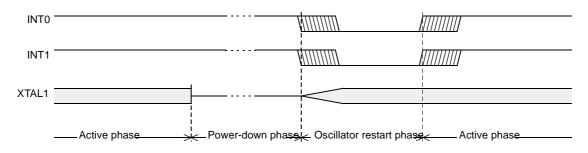
Table 14. IPH RegisterIPH - Interrupt Priority High Register (B7h)

7	6	5	4	3	2	1	0
-	-	PT2H	PSH	PT1H	PX1H	РТ0Н	PX0H
Bit Number	Bit Mnemonic	Description					
7	-	Reserved The value re	ad from this b	oit is indetermi	nate. Do not s	et this bit.	
6	-	Reserved The value re	Reserved The value read from this bit is indeterminate. Do not set this bit.				
5	PT2H		0 0 Lowest 0 1 1 0				
4	PSH		0 0 Lowest 0 1 1 0				
3	PT1H		Timer 1 overflow interrupt Priority High bit PT1H PT1 Priority Level 0 0 Lowest 0 1 1 0				
2	PX1H		External interrupt 1 Priority High bit <u>PX1H</u> <u>PX1</u> <u>Priority Level</u> 0 0 Lowest 0 1 1 0				
1	РТОН		PTOH PTO Priority Level 0 0 Lowest 0 1 1 0				
0	РХОН	External inte <u>PX0H</u> <u>P</u> 2 0 0 0 1 1 0 1 1	rrupt 0 Priorit <u>;</u> <u>X0 Priority Le</u> Lowest Highest	y High bit <u>evel</u>			

Reset Value = XX00 0000b Not bit addressable

Idle Mode	An instruction that sets PCON.0 causes that to be the last instruction executed before going into the Idle mode. In the Idle mode, the internal clock signal is gated off to the CPU, but not to the interrupt, Timer, and Serial Port functions. The CPU status is preserved in its entirely: the Stack Pointer, Program Counter, Program Status Word, Accumulator and all other registers maintain their data during Idle. The port pins hold the logical states they had at the time Idle was activated.
	There are two ways to terminate the Idle. Activation of any enabled interrupt will cause PCON.0 to be cleared by hardware, terminating the Idle mode. The interrupt will be serviced, and following RETI the next instruction to be executed will be the one following the instruction that put the device into idle.
	The flag bits GF0 and GF1 can be used to give an indication if an interrupt occured dur- ing normal operation or during an Idle. For example, an instruction that activates Idle can also set one or both flag bits. When Idle is terminated by an interrupt, the interrupt service routine can examine the flag bits.
	The other way of terminating the Idle mode is with a hardware reset. Since the clock oscillator is still running, the hardware reset needs to be held active for only two machine cycles (24 oscillator periods) to complete the reset.
Power-Down Mode	To save maximum power, a power-down mode can be invoked by software (Refer to Table 10., PCON register).
	In power-down mode, the oscillator is stopped and the instruction that invoked power- down mode is the last instruction executed. The internal RAM and SFRs retain their value until the power-down mode is terminated. V _{CC} can be lowered to save further power. Either a hardware reset or an external interrupt can cause an exit from power- down. To properly terminate power-down, the reset or external interrupt should not be executed before V _{CC} is restored to its normal operating level and must be held active long enough for the oscillator to restart and stabilize.
	Only external interrupts INTO and INT1 are useful to exit from power-down. For that, interrupt must be enabled and configured as level or edge sensitive interrupt input.
	Holding the pin low restarts the oscillator but bringing the pin high completes the exit as detailed in Figure 11. When both interrupts are enabled, the oscillator restarts as soon as one of the two inputs is held low and power down exit will be completed when the first input will be released. In this case the higher priority interrupt service routine is executed.





Exit from power-down by reset redefines all the SFRs, exit from power-down by external interrupt does no affect the SFRs.





Exit from power-down by either reset or external interrupt does not affect the internal RAM content.

Note: If idle mode is activated with power-down mode (IDL and PD bits set), the exit sequence is unchanged, when execution is vectored to interrupt, PD and IDL bits are cleared and idle mode is not entered.

Mode	ode Program Memory PO		PORT3	PORT4
Idle	Internal	Port Data	Port Data	Port Data
Power Down	Power Down Internal		Port Data	Port Data

Reduced EMI Mode

As there is no Port 0 nor Port 2 outputted from this device, there is no need to output ALE. EMI are then reduced intrinsically.

The bit which controls ALE disabling in Rx devices is A0 (bit 0) in register AUXR. As explained earlier for bit EXTRAM, writing any value to AO will have no effect on the device behavior.

Table 16. AUXR RegisterAUXR - Auxiliary Register (8Eh)

7	6	5	4	3	2	1	0	
-	-	-	-	-	-	EXTRAM	AO	
Bit Number	Bit Mnemoni	c Descript	Description					
7	-	Reserved The value read from this bit is indeterminate. Do not set this bit.						
6	-	Reserved The value	Reserved The value read from this bit is indeterminate. Do not set this bit.					
5	-		Reserved The value read from this bit is indeterminate. Do not set this bit.					
4	-		Reserved The value read from this bit is indeterminate. Do not set this bit.					
3	-		Reserved The value read from this bit is indeterminate. Do not set this bit.					
2	-	Reserved The value	-	is bit is indete	rminate. Do n	ot set this bit.		
1	EXTRAM	1 Writing to	EXTRAM bit Writing to this bit will have no effect. The value read from this bit is indeterminate.				s	
0	AO	Writing to	ALE Output bit Writing to this bit will have no effect. The value read from this bit is indeterminate.					

Reset Value = XXXX XX00b Not bit addressable





T83C5101/02 ROM

ROM Structure

The T83C5101/02 ROM memory is divided in three different arrays:

- the code array
 - T83C5101: 16 KB
 - T83C5102: 8 KB
- the encryption array: 64 bytes
- the signature array: 4 bytes

ROM Lock System The program Lock system, when programmed, protects the on-chip program against software piracy.

Encryption Array Within the ROM array are 64 bytes of encryption array. Every time a byte is addressed during program verify, 6 address lines are used to select a byte of the encryption array. This byte is then exclusive-NOR'ed (XNOR) with the code byte, creating an encrypted verify byte. The algorithm, with the encryption array in the unprogrammed state, will return the code in its original, unmodified form.

When using the encryption array, one important factor needs to be considered. If a byte has the value FFh, verifying the byte will produce the encryption byte value. If a large block (>64 bytes) of code is left unprogrammed, a verification routine will display the content of the encryption array. For this reason all the unused code bytes should be programmed with random values.

Program Lock Bits The lock bits when programmed according to Table 17. will provide different level of protection for the on-chip code and data.

Program Lock Bits				
Security level	LB1	LB2	LB3	Protection Description
1	U	U	U	No program lock features enabled. Code verify will still be encrypted by the encryption array if programmed.
2	Ρ	U	U	Not applicable as usually this protection deals with executing MOVC from external memory (impossible) and sampling EA pin (doesn't exist any more)
3	U	Ρ	U	Verify disable. This security level is available because ROM integrity will be verified thanks to another method.

Table 17. Program Lock Bits

U: unprogrammed P: programmed

Signature Bytes

The T8xC5101/02 family contains 4 factory programmed signatures bytes. To read these bytes, perform the process described in sections Section "Definition of Terms" and Section "Signature Bytes".

Verify Algorithm Refer to Section "Verifying Algorithm", page 36

T87C5101 EPROM

EPROM Structure

The T87C5101 EPROM is divided into two different arrays:

- the code array: 16 KB
- the encryption array: 64 bytes

In addition a third non programmable array is implemented:

• the signature array: 4 bytes.

EPROM Lock System The program Lock system, when programmed, protects the on-chip program against software piracy.

Encryption Array Within the EPROM array are 64 bytes of encryption array that are initially unprogrammed (all FF's). Every time a byte is addressed during program verify, 6 address lines are used to select a byte of the encryption array. This byte is then exclusive-NOR'ed (XNOR) with the code byte, creating an encrypted verify byte. The algorithm, with the encryption array in the unprogrammed state, will return the code in its original, unmodified form.

When using the encryption array, one important factor needs to be considered. If a byte has the value FFh, verifying the byte will produce the encryption byte value. If a large block (>64 bytes) of code is left unprogrammed, a verification routine will display the content of the encryption array. For this reason all the unused code bytes should be programmed with random values.

Program Lock BitsThe three lock bits, when programmed according to Table 18, will provide different level
of protection for the on-chip code and data.

Program Lock Bits				
Security level LB1 LB2 LB3		LB3	Protection Description	
1	U	U	U	No program lock features enabled. Code verify will still be encrypted by the encryption array if programmed.
2	Р	U	U	Further programming of the program memory is disabled.
3	U	Р	U	Same as security level 2 + verify disabled.
4	U	U	Р	Not applicable as usually this protection deals with external execution, which is impossible with this device.

 Table 18.
 Program Lock Bits

U: unprogrammed,

P: programmed

WARNING: Security level 2 and higher should only be programmed after EPROM verification.

Signature Bytes

The T8xC5101/02 family contains 4 factory programmed signatures bytes. To read these bytes, perform the process described in section and .





EPROM Programming

Set-up Modes	In order to program and verify the EPROM or to read the signature bytes, the T87C5101
	is placed in specific test modes (See Figure 12.).

Control and program signals must be held at the levels indicated in Table 19.

Port 1

Definition of Terms Address and Control Lines: RST, TEST, Port 3

Data Lines:

Program Signals: V_{PP}, PROG

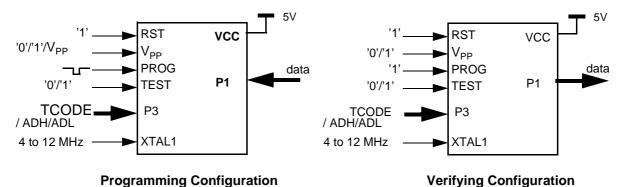
Table 19. EPROM Set-Up Modes

Mode	RST	TEST	PROG	VPP	P3.7	P3.6	P3.3	P3.2	P3.1
Program Code data	1	0/1	Ŀ	0/ 12.75V	1	1	1	1	0
Verify Code data	1	0/1	1	0/1	1	1	0	0	0
Program Encryption Array Address 0-3Fh	1	0/1	<u>.</u>	0/ 12.75V	1	0	1	1	0
Read Signature Bytes	1	0	1	0	0	0	0	0	0
Program Lock bit 1	1	0/1	<u>.</u>	0/ 12.75V	1	1	1	1	1
Program Lock bit 2	1	0/1	1.1.	0/ 12.75V	0	0	1	1	1
Program Lock bit 3	NA	NA	NA	NA	NA	NA	NA	NA	NA
Read lock bits	1	0	1	0	1	0	0	0	0

NA: not applicable

Figure 12. Programming and Verifying Modes Configuration

TCODE = Test code, ADH = address high, ADL = address low



EPROM Programming and Verification Characteristics

 T_A = 21°C to 27°C; V_{SS} = 0V; V_{CC} = 5V \pm 10% while programming. V_{CC} = operating range while verifying.

 Table 20.
 EPROM Programming Parameters

Symbol	Parameter	Min	Мах	Units
V _{PP}	Programming Supply Voltage	12.5	13	V
I _{PP}	Programming Supply Current		75	mA
1/T _{CLCL}	Oscillator Frequency	4	12	MHz

Programming Algorithm

- step 1: V_{PP} and TEST low, present T code for programming on P3 and raise V_{PP} to 12.75V
- step 2: present Address High on P3 and pulse TEST high
- step 3: present address Low on P3 and data on P1
- step 4: pulse PROG low
- step 5: back to step 3 if the next byte to program is in the same 256 byte page OR
- step 5: back to step 2 if the next byte to program is in a different page



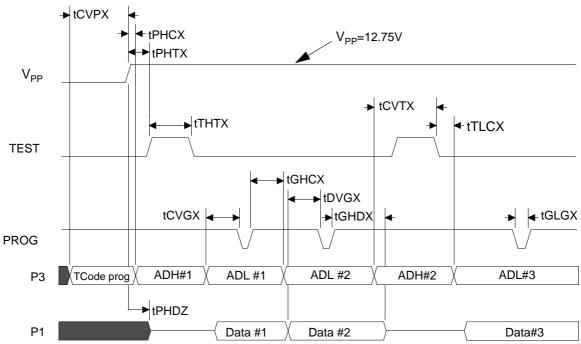


Table 21.	Programming	Algorithm	Parameters

				12 MHz	
Symbol	Parameter	Formula	Min	Мах	Unit
tOSC	Oscillator period	-		83.3	ns
tCVPX	Code input Valid to V_{PP} rising edge setup time	36 tOSC	3		μs





			12	MHz	
Symbol	Parameter	Formula	Min	Max	Unit
tPHCX	Code input valid from V_{PP} High hold time	1 tOSC	83.3		ns
tPHTX	Test input valid from V_{PP} High hold time	1 tOSC	83.3		ns
tTHTX	Test High pulse width	36 tOSC	3		μs
tCVTX	Address high Valid to Test falling edge setup time	36 tOSC	3		μs
tTLCX	Address input Valid from Test falling edge hold time	1 tOSC	83.3		ns
tPHDZ	Data output Hi-Z from V_{PP} high delay			0	
tGLGX	Prog Low pulse width		90	110	μs
tCVGX	Address valid to Prog falling edge setup time	36 tOSC	3		μs
tDVGX	Data input Valid to Prog falling edge setup time	36 tOSC	3		μs
tGHCX	Address valid from Prog rising edge hold time	1 tOSC	83.3		ns
tGHDX	Data input valid from Prog rising edge hold time	1 tOSC	83.3		ns

Table 21. Programming Algorithm Parameters (Continued)

Verifying Algorithm

- step 1: V_{PP} and TEST low, present T code for verification on P3 and Raise V_{PP} to Vcc
- step 2: present address High and pulse TEST high
- step 3: present address Low on P3 and read data on P1
- step 4: back to step 3 if the next byte is in the same 256 byte page

OR

• step 4: back to step 2 if the next byte to program is in a different page

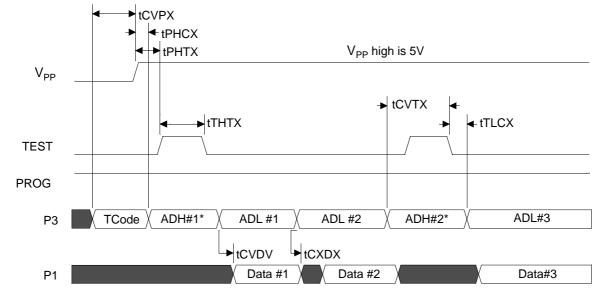


Figure 14. Verifying Signals Waveform

Note: * ADH is egal to 0 when addressing signature bytes

T8xC5101/02

Table 22.	Verify	Algorithm	Parameters
-----------	--------	-----------	------------

			12	MHz	
Symbol	Parameter	Formula	Min	Max	Unit
tOSC	Oscillator period			83.3	ns
tCVPX	Code input Valid to V_{PP} rising edge setup time	36 tOSC	3		μs
tPHCX	Code input valid from V_{PP} High hold time	1 tOSC	83.3		ns
tPHTX	Test input valid from V_{PP} High hold time	1 tOSC	83.3		ns
tTHTX	Test High pulse width	36 tOSC	3		μs
tCVTX	Address high Valid to Test falling edge setup time	36 tOSC	3		μs
tTLCX	Address input Valid from Test falling edge hold time	1 tOSC	83.3		ns
tCVDV	Address Valid to Data output Valid delay	36 tOSC		3	μs
tCXDX	Data valid from Address Invalid hold time		0		

Programming/Verify Algorithm

- step 1: V_{PP} and TEST low, present T code for programming on P3 and raise V_{PP} to 12.75V
- step 2: present Address High on P3 and pulse TEST high
- step 3: present address Low on P3 and data on P1
- step 4: pulse PROG low
- step 5: present T code for verifying on P3 and lower V_{PP} to 0V
- step 6: read previous data
- step 7: present T code for programming on P3 and raise V_{PP} to 12.75V
- step 8: goto step 3 if the next byte to program is in the same 256 byte page

OR

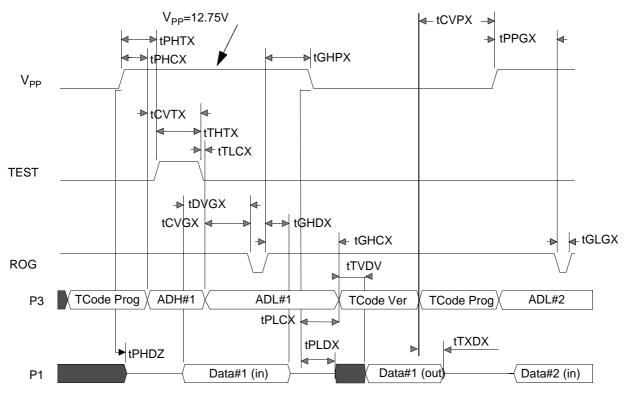
•

• step 8: goto step 2 if the next byte to program is in a different page









Note: after programming, addresses high and low are already latched in the device, and when switching to verify, the device outputs directly the last written data.

Symbol	Parameter	Formula	Min	Max	Unit
tOSC	Oscillator period	-		83.3	ns
tCVPX	Code input Valid to V_{PP} rising edge setup time	36 tOSC	3		μs
tPHCX	Code input valid from V_{PP} High hold time	1 tOSC	83.3		ns
tPHTX	Test input valid from V_{PP} High hold time	1 tOSC	83.3		ns
tTHTX	Test High pulse width	36 tOSC	3		μs
tCVTX	Address high Valid to Test falling edge setup time	36 tOSC	3		μs
tTLCX	Address input Valid from Test falling edge hold time	1 tOSC	83.3		ns
tPHDZ	Data output Hi-Z from V_PP high delay			0	
tGLGX	Prog Low pulse width		90	110	μs
tCVGX	Address valid to Prog falling edge setup time	36 tOSC	3		μs
tDVGX	Data input Valid to Prog falling edge setup time	36 tOSC	3		μs
tGHCX	Address valid from Prog rising edge hold time	1 tOSC	83.3		ns
tGHDX	Data input valid from Prog High hold time	1 tOSC	83.3		ns
tGHPX	V_{PP} on V_{PP} pin from Prog High hold time	36 tOSC	3		μs

Table 23. Programming/Verifying Signnal's Wavaform Parameters

				VIHz	
Symbol	Parameter	Formula	Min	Мах	Unit
tTXDX	Data output valid from T code invalid hold time		0		
tTVDV	Data output valid from T code valid delay	36 tOSC		3	μs
tPLCX	Address valid from V_{PP} falling edge hold time	36 tOSC	3		μs
tPPGX	V_{PP} on V_{PP} pin to Prog falling edge setup time	36 tOSC	3		μs
tPLDX	Data output from V_{PP} Low delay		0		μs

Table 23. Programming/Verifying Signnal's Wavaform Parameters (Continued)

Lock Bits Programming and Verification

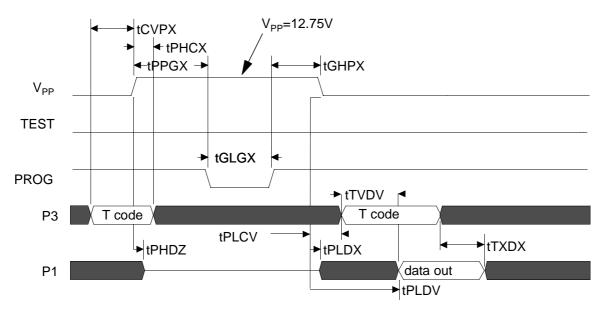
Programming:

 step 1: V_{PP} and TEST low, present T code for Lock bits programming on P3 and raise V_{PP} to 12.75V

Verification:

- step 2: pulse PROG low
- step 1: V_{PP} and TEST low, present T code for Lock bits verification
- step 2: read data

Figure 16. Lock Bits Programming Signals Waveform and Lock Bits Verifying Signals Waveform



				MHz	
Symbol	Parameter	Formula	Min	Мах	Unit
tOSC	Oscillator period	-		83.3	ns





Table 24. Lock Bits Programming Signals Waveform and Lock Bits Verifying Signals

 Waveform Parameters (Continued)

			12	MHz	
Symbol	Parameter	Formula	Min	Max	Unit
tCVPX	Code input valid to $V_{\mbox{\scriptsize PP}}$ rising edge setup time	36 tOSC	3		μs
tPHCX	Code input valid from V_{PP} high hold time	1 tOSC	83.3		ns
tPPGX	V_{PP} on V_{PP} pin to PROG Low setup time	36 tOSC	3		μs
tGLGX	Prog Low pulse width		90	110	μs
tGHPX	V_{PP} on V_{PP} pin from PROG High hold time	36 tOSC	3		μs
tPLDV	Data Output Valid from V_{PP} Low delay	36 tOSC		3	μs
tPLDX	Data output from V_{PP} Low delay		0		
tTVDV	Data output valid from T code valid delay	36 tOSC		3	μs
tTXDX	Data output valid from T code invalid hold time		0		
tPHDZ	Data output Hi-Z from V_{PP} high delay			0	
tPLCV	$V_{\mbox{\scriptsize PP}}$ low to T code valid setup time	36 tOSC	3		μs

V_{PP} pin in driven:

- to 0V when P3 contains the test code
- to 5V when P3 contains high order or low order addresses
- to V_{PP} during programming cycled
- Test pin is driven:
- to 5V when P3 contains high order address
- to 0V in the other cases

EPROM Erasure (Windowed Packages Only)

Erasing the EPROM erases the code array, the encryption array and the lock bits returning the parts to full functionality.

Erasure leaves all the EPROM cells in a 1's state (FF).

Erasure Characteristics

The recommended erasure procedure is exposure to ultraviolet light (at 2537 Å) to an integrated dose at least 15 W-sec/cm². Exposing the EPROM to an ultraviolet lamp of 12,000 μ W/cm² rating for 30 minutes, at a distance of about 25 mm, should be sufficient. An exposure of 1 hour is recommended with most of standard erasers.

Erasure of the EPROM begins to occur when the chip is exposed to light with wavelength shorter than approximately 4,000 Å. Since sunlight and fluorescent lighting have wavelengths in this range, exposure to these light sources over an extended time (about 1 week in sunlight, or 3 years in room-level fluorescent lighting) could cause inadvertent erasure. If an application subjects the device to this type of exposure, it is suggested that an opaque label be placed over the window.

Signature Bytes

Signature Bytes Content

The T8xC5101/02 has four signature bytes in location 30h, 31h, 60h and 61h. To read these bytes follow the procedure for EPROM verify but activate the control lines provided in Table 19. for Read Signature Bytes. Table 25. shows the content of the signature byte for the T8xC5101/02.

Table 25. Signature Bytes Content

Location	Contents	Comment
30h	58h	Manufacturer Code: Atmel
31h	57h	Family Code: C51 X2
60h	3Bh	Product name: T83C5101/02 8K or 16K ROM version
60h	BBh	Product name: T87C5101 16K OTP version
61h	EFh	Product revision number: T8xC5101/02 Rev.0





Electrical Characteristics

Table 26. Absolute Maximum Ratings

C = commercial0°C to 70°C	*NOTICE: Stresses at or above those listed under " Abso- lute Maximum Ratings" may cause permanent
I = industrial40°C to 85°C	damage to the device. This is a stress rating only and functional operation of the device at these or
Storage Temperature65°C to + 150°C	any other conditions above those indicated in the operational sections of this specification is not
Voltage on V _{CC} to V _{SS} 0.5 V to + 7 V	implied. Exposure to absolute maximum rating conditions may affect device reliability.
Voltage on V _{PP} to V _{SS} 0.5 V to + 13 V	Power Dissipation value is based on the maxi-
Voltage on Any Pin to $\rm V_{SS}$ 0.5 V to $\rm V_{CC}$ + 0.5 V	mum allowable die temperature and the thermal resistance of the package.
Power Dissipation	

Power Consumption Measurement Since the introduction of the first C51 devices, every manufacturer made operating lcc measurements under reset, which made sense for the designs were the CPU was running under reset. In Atmel new devices, the CPU is no more active during reset, so the power consumption is very low but is not really representative of what will happen in the customer system. That's why, while keeping measurements under Reset, Atmel presents a new way to measure the operating lcc:

Using an internal test ROM, the following code is executed:

Label: SJMP Label (80 FE)

Ports 1, 3, 4 are disconnected, RST = Vss, XTAL2 is not connected and XTAL1 is driven by the clock.

This is much more representative of the real operating Icc.

DC Parameters for Standard Voltage

 $\begin{array}{l} T_{A}=0^{\circ}C \text{ to } +70^{\circ}C; \ V_{SS}=0 \ V; \ V_{CC}=5 \ V\pm10\%; \ F=0 \ \text{to } 40 \ \text{MHz}. \\ T_{A}=-40^{\circ}C \ \text{to } +85^{\circ}C; \ V_{SS}=0 \ V; \ V_{CC}=5 \ V\pm10\%; \ F=0 \ \text{to } 40 \ \text{MHz}. \end{array}$

Table 27.	DC Parameters in Standard	Voltage
-----------	---------------------------	---------

Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
V _{IL}	Input Low Voltage	-0.5		0.2 V _{CC} - 0.1	V	
V _{IH}	Input High Voltage except XTAL1, RST	0.2 V _{CC} + 0.9		V _{CC} + 0.5	V	
V _{IH1}	Input High Voltage, XTAL1, RST	0.7 V _{CC}		V _{CC} + 0.5	V	
V _{OL}	Output Low Voltage, ports 1, 3, 4.2-4.5 ⁽⁶⁾			0.3 0.45 1.0	V V V	$I_{OL} = 100 \ \mu A$ $I_{OL} = 1.6 \ m A$ $I_{OL} = 3.5 \ m A$
V _{OL1}	Output Low Voltage, port 4.0-4.1 ⁽⁶⁾		0.76 ⁽⁵⁾	0.5 1.0	V V V	$I_{OL} = 10.0 \text{ mA}$ $I_{OL} = 6.0 \text{ mA}$ $I_{OL} = 12.0 \text{ mA}$
V _{OH}	Output High Voltage, ports 1, 3, 4.2-4.5 ⁽⁶⁾	V _{CC} - 0.3 V _{CC} - 0.7 V _{CC} - 1.5			V V V	I _{OH} = -10 μA I _{OH} = -30 μA I _{OH} = -60 μA V _{CC} = 5 V ± 10%
R _{RST}	RST Pulldown Resistor	50	90 (5)	200	kΩ	
I _{IL}	Logical 0 Input Current ports 1, 3 and 4			-50 TBD	μA	Vin = 0.45 V, port 1 & 3 Vin = 0.45 V, port 4
ILI	Input Leakage Current			±10	μΑ	0.45 V < Vin < V _{CC}
I _{TL}	Logical 1 to 0 Transition Current, ports 1, 3			-650 TBD	μΑ	Vin = 2.0 V, port 1 & 3 Vin = 2.0 V, port 4
C _{IO}	Capacitance of I/O Buffer			10	pF	Fc = 1 MHz TA = 25°C
I _{PD}	Power Down Current	to be confirmed	20 (5)	50	μA	$2.0 \text{ V} < \text{V}_{\text{CC}} < 5.5 \text{ V}^{(3)}$
I _{CC} under RESET	Power Supply Current Maximum values, X1 mode: ⁽⁷⁾		to be confirmed	1 + 0.4 Freq (MHz) @12MHz 5.8 @16MHz 7.4	mA	$V_{CC} = 5.5 V^{(1)}$
I _{CC} operating	Power Supply Current Maximum values, X1 mode: ⁽⁷⁾		to be confirmed	3 + 0.6 Freq (MHz) @12MHz 10.2 @16MHz 12.6	mA	V _{CC} = 5.5 V ⁽⁸⁾
I _{CC} idle	Power Supply Current Maximum values, X1 mode: ⁽⁷⁾		to be confirmed	0.25+0.3 Freq (MHz) @12MHz 3.9 @16MHz 5.1	mA	V _{CC} = 5.5 V ⁽²⁾





DC Parameters for Low $\begin{array}{l} T_{A}=0^{\circ}C \text{ to } +70^{\circ}C; \ V_{SS}=0 \ V; \ V_{CC}=2.7 \ V \text{ to } 5.5 \ V; \ F=0 \text{ to } 30 \ MHz. \\ T_{A}=-40^{\circ}C \text{ to } +85^{\circ}C; \ V_{SS}=0 \ V; \ V_{CC}=2.7 \ V \text{ to } 5.5 \ V; \ F=0 \text{ to } 30 \ MHz. \end{array}$ Voltage

Table 28. DC Parameters for Low Voltage

Symbol	Parameter	Min	Тур	Мах	Unit	Test Conditions
V _{IL}	Input Low Voltage	-0.5		0.2 V _{CC} - 0.1	V	
V _{IH}	Input High Voltage except XTAL1, RST	0.2 V _{CC} + 0.9		V _{CC} + 0.5	V	
V _{IH1}	Input High Voltage, XTAL1, RST	0.7 V _{CC}		V _{CC} + 0.5	V	
V _{OL}	Output Low Voltage, ports 1, 3, 4.2-4.5 (6)			0.45	V	I _{OL} = 0.8 mA
V _{OL1}	Output Low Voltage, port 4.0-4.1 ⁽⁶⁾		0.83 ⁽⁵⁾	0.5	V V	I _{OL} = 10.0 mA I _{OL} = 4.8 mA
V _{OH}	Output High Voltage, ports 1, 3, 4.2-4.5 (6)	0.9 V _{CC}			V	I _{OH} = -10 μA
I _{IL}	Logical 0 Input Current ports 1, 2 and 3			-50 TBD	μA	Vin = 0.45 V, port 1 & 3 Vin = 0.45 V, port 4
ILI	Input Leakage Current			±10	μΑ	0.45 V < Vin < V _{CC}
I _{TL}	Logical 1 to 0 Transition Current, ports 1, 3			-650 TBD	μΑ	Vin = 2.0 V, port 1 & 3 Vin = 2.0 V, port 4
R _{RST}	RST Pulldown Resistor	50	90 (5)	200	kΩ	
CIO	Capacitance of I/O Buffer			10	pF	Fc = 1 MHz T _A = 25°C
I _{PD}	Power Down Current	to be confirmed	20 ⁽⁵⁾ 10 ⁽⁵⁾	50 30	μA	$V_{CC} = 2.0 \text{ V to } 5.5 \text{ V}^{(3)}$ $V_{CC} = 2.0 \text{ V to } 3.3 \text{ V}^{(3)}$
I _{CC} under RESET	Power Supply Current Maximum values, X1 mode: ⁽⁷⁾		to be confirmed	1 + 0.2 Freq (MHz) @12MHz 3.4 @16MHz 4.2	mA	$V_{CC} = 3.3 V^{(1)}$
I _{CC} operating	Power Supply Current Maximum values, X1 mode: (7)		to be confirmed	1 + 0.3 Freq (MHz) @12MHz 4.6 @16MHz 5.8	mA	$V_{CC} = 3.3 V^{(8)}$
l _{CC} idle	Power Supply Current Maximum values, X1 mode: (7)		to be confirmed	0.15 Freq (MHz) + 0.2 @12MHz 2 @16MHz 2.6	mA	$V_{CC} = 3.3 V^{(2)}$

Notes:

I_{CC} under reset is measured with all output pins disconnected; XTAL1 driven with T_{CLCH}, T_{CHCL} = 5 ns (see Figure 21.), V_{IL} = V_{SS} + 0.5 V, V_{IH} = V_{CC} - 0.5V; XTAL2 N.C.; V_{PP} = RST = V_{CC}. I_{CC} would be slightly higher if a crystal oscillator used.
 Idle I_{CC} is measured with all output pins disconnected; XTAL1 driven with T_{CLCH}, T_{CHCL} = 5 ns, V_{IL} = V_{SS} + 0.5 V, V_{IH} = V_{CC} - 0.5V; (state 2 N c), V_{IL} = V_{CC} - 0.5V; (state 2 N c), V_{IL} = V_{CC} - 0.5V; (state 2 N c), V_{IL} = V_{SS} + 0.5 V, V_{IH} = V_{CC} - 0.5V; (state 2 N c), V_{IL} = V_{SS} + 0.5 V, V_{IH} = V_{CC} - 0.5V; (state 2 N c), V_{IL} = V_{SS} + 0.5 V, V_{IH} = V_{CC} - 0.5V; (state 2 N c), V_{IL} = V_{SS} + 0.5 V, V_{IH} = V_{CC} - 0.5V; (state 2 N c), V_{IL} = V_{SS} + 0.5 V, V_{IH} = V_{CC} - 0.5V; (state 2 N c), V_{IL} = V_{SS} + 0.5 V, V_{IH} = V_{CC} - 0.5V; (state 2 N c), V_{IL} = V_{SS} + 0.5 V, V_{IH} = V_{CC} - 0.5V; (state 2 N c), V_{IL} = 0.5V; (state 2 N c),

0.5 V; XTAL2 N.C; V_{PP} = RST = V_{SS} (see Figure 19.).

3. Power Down I_{CC} is measured with all output pins disconnected; $V_{PP} = V_{SS}$; XTAL2 NC.; RST = V_{SS} (see Figure 20).

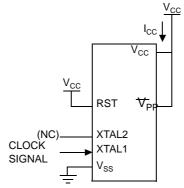
4. Not Applicable

5. Typicals are based on a limited number of samples and are not guaranteed. The values listed are at room temperature and 5V.

- 6. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows: Maximum I_{OL} per port pin: 10 mA Maximum I_{OL} per 6 and 8-bit port: Port 4.0 + 4.1: 20 mA Port 4.2 to 4.5: 8 mA Ports 1 and 3: 15 mA Maximum total I_{OL} for all output pins: 58 mA If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.
- 7. For other values, please contact your sales office.
- Operating I_{CC} is measured with all output pins disconnected; XTAL1 driven with T_{CLCH}, T_{CHCL} = 5 ns (see Figure 21.), V_{IL} = V_{SS} + 0.5 V,

 $V_{IH} = V_{CC} - 0.5V$; XTAL2 N.C.; $V_{PP} = V_{CC}$; RST = V_{SS} . The internal ROM runs the code 80 FE (label: SJMP label). I_{CC} would be slightly higher if a crystal oscillator is used. Measurements are made with OTP products when possible, which is the worst case.





All other pins are disconnected.

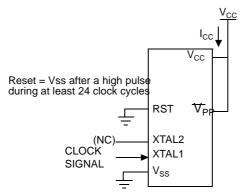


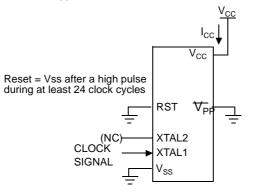
Figure 18. Operating I_{CC} Test Condition

All other pins are disconnected.

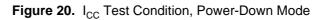


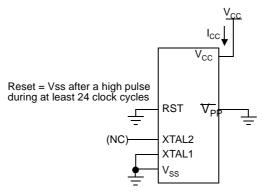




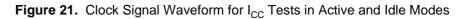


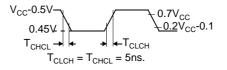
All other pins are disconnected.





All other pins are disconnected.





AC Parameters

Explanation of the AC Symbols

Each timing symbol has 5 characters. The first character is always a "T" (stands for Time). The other characters, depending on their positions, stand for the name of a signal or the logical status of that signal. The following is a list of all the characters and what they stand for.

Example: T_{XHDV} = Time from clock rising edge to input data valid.

TA = 0 to +70°C (commercial temperature range); V_{SS} = 0 V; V_{CC} = 5 V \pm 10%; -V ranges.

T_A = 0 to +70°C (commercial temperature range); V_{SS} = 0 V; 2.7 V < V_{CC} < 5.5 V; -L range.

TA = -40°C to +85°C (industrial temperature range); V_{SS} = 0 V; 2.7 V < V_{CC <} 5.5 V; -L range.

Table 29. gives the maximum applicable load capacitance for Port 1, 3 and 4. Timings will be guaranteed if these capacitances are respected. Higher capacitance values can be used, but timings will then be degraded.

Table 29. Load Capacitance versus speed range, in pF

	-V	-L
Port 1, 3 & 4	50	80

Table 31 gives the description of each AC symbols.

Table 31 gives for each range the AC parameter.

Table 32 gives the frequency derating formula of the AC parameter. To calculate each AC symbols, take the x value corresponding to the speed grade you need (-V or -L) and replace this value in the formula. Values of the frequency must be limited to the corresponding speed grade:

Table 30. Max frequency for derating formula regarding the speed grade

	-V X1 mode	-V X2 mode	-L X1 mode	-L X2 mode
Freq (MHz)	40	33	40	20
T (ns)	25	30	25	50

Example:

 T_{XHDV} in X2 mode for a -V part at 20 MHz (T = 1/20^{E6} = 50 ns):

x= 133 (Table 32.)

T= 50ns

 $T_{XHDV} = 5T - x = 5 \times 50 - 133 = 117$ ns





Serial Port Timing - Shift Register Mode

Symbol	Parameter
T _{XLXL}	Serial port clock cycle time
T _{QVHX}	Output data set-up to clock rising edge
T _{XHQX}	Output data hold after clock rising edge
T _{XHDX}	Input data hold after clock rising edge
T _{XHDV}	Clock rising edge to input data valid

Table 31. AC Parameters for a Fix Clock

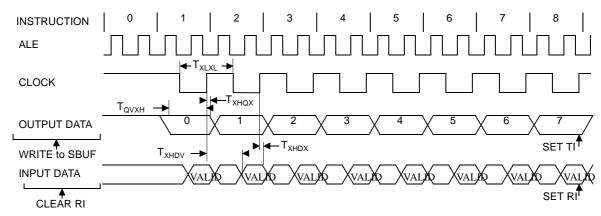
Speed	X2 n 33 l	V node MHz z equiv.	י- standar 40 M	-	20	L node MHz z equiv.		L d mode MHz	Units
Symbol	Min	Max	Min	Max	Min	Max	Min	Max	
T _{XLXL}	180		300		300		300		ns
T _{QVHX}	100		200		200		200		ns
T _{XHQX}	10		30		30		30		ns
T _{XHDX}	0		0		0		0		ns
T _{XHDV}		17		117		117		117	ns

Table 32. AC Parameters for a Variable Clock: derating formula

Symbol	Туре	Standard Clock	X2 Clock	-V	-L	Units
T _{XLXL}	Min	12 T	6 T			ns
T _{QVHX}	Min	10 T - x	5 T - x	50	50	ns
T _{XHQX}	Min	2 T - x	T - x	20	20	ns
T _{XHDX}	Min	х	х	0	0	ns
T _{XHDV}	Max	10 T - x	5 T- x	133	133	ns

Shift Register Timing Waveforms

Figure 22. Shift Register Timing Waveforms

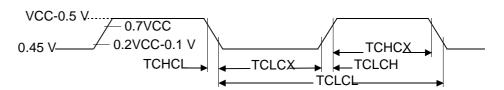


External Clock Drive Characteristics (XTAL1)

Symbol	Parameter	Min	Мах	Units
T _{CLCL}	Oscillator Period	25		ns
T _{CHCX}	High Time	5		ns
T _{CLCX}	Low Time	5		ns
T _{CLCH}	Rise Time		5	ns
T _{CHCL}	Fall Time		5	ns
T _{CHCX} /T _{CLCX}	Cyclic ratio in X2 mode	40	60	%

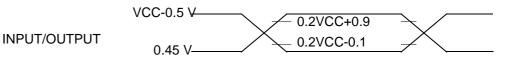
External Clock Drive Waveforms

Figure 23. External Clock Drive Waveforms



AC Testing Input/Output Waveforms

Figure 24. AC Testing Input/Output Waveforms



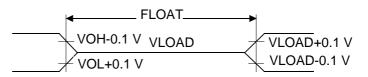
AC inputs during testing are driven at V_{CC} - 0.5 for a logic "1" and 0.45V for a logic "0". Timing measurement are made at V_{IH} min for a logic "1" and V_{IL} max for a logic "0".





Float Waveforms

Figure 25. Float Waveforms



For timing purposes as port pin is no longer floating when a 100 mV change from load voltage occurs and begins to float when a 100 mV change from the loaded V_{OH}/V_{OL} level occurs. I_{OL}/I_{OH} $\geq \pm$ 20mA.

Clock Waveforms Valid in normal clock mode. In X2 mode XTAL2 signal must be changed to XTAL2 divided by two.

Figure 26. Clock Waveforms

INTERNAL CLOCK	STATE4 P1P2	STATE5 P1P2	STATE6 P1P2	STATE1 P1P2	STATE2 P1P2	STATE3 P1P2	STATE4 P1P2	STATE5 P1P2	
XTAL2									Ĺſ
PORT OPERA	TION								
		(OLD DATA	NEW DATA	\				
MOV DEST PO (INCLUDE <u>S IN</u>			P3, P4 PIN	NS SAMPLE	D	P1, P3,	P4 PINS SA	MPLED	<u> </u>
SERIAL PORT TXD (M	MODE 0)	CK RXI ∢♥→	D SAMPLEE)		1		RX ∢♥▶	D SAM

This diagram indicates when signals are clocked internally. The time it takes the signals to propagate to the pins, however, ranges from 25 to 125 ns. This propagation delay is dependent on variables such as temperature and pin loading. Propagation also varies from output to output and component. Typically though ($T_A=25^{\circ}C$ fully loaded) RD and WR propagation delays are approximately 50ns. The other signals are typically 85 ns. Propagation delays are incorporated in the AC specifications.

Ordering Information

 Table 33.
 Maximum Clock Frequency

Code	-V	-L	Unit
Standard Mode, oscillator frequency Standard Mode, internal frequency	40 40	40 40	MHz
X2 Mode, oscillator frequency X2 Mode, internal equivalent frequency	33 66	20 40	MHz

Table 34. Possible Order Entries

Part Number	Memory Size	Supply Voltage	Temperature Range	Speed (MHz)	Package	Packing
T83C5101xxx-3ZSCL	16K ROM	2.7 - 5.5V	Commercial	40	DIL24	Stick
T83C5101xxx-3ZSCV	16K ROM	5V	Commercial	66	DIL24	Stick
T83C5101xxx-3ZSIL	16K ROM	2.7 - 5.5V	Industrial	40	DIL24	Stick
T83C5101xxx-TDSCL	16K ROM	2.7 - 5.5V	Commercial	40	S024	Stick
T83C5101xxx-TDSCV	16K ROM	5V	Commercial	66	S024	Stick
T83C5101xxx-TDSIL	16K ROM	2.7 - 5.5V	Industrial	40	S024	Stick
T83C5101xxx-TDRCL	16K ROM	2.7 - 5.5V	Commercial	40	S024	Tape & Reel
T83C5101xxx-TDRCV	16K ROM	5V	Commercial	66	S024	Tape & Reel
T83C5101xxx-TDRIL	16K ROM	2.7 - 5.5V	Industrial	40	S024	Tape & Reel
T83C5101xxx-TISCL	16K ROM	2.7 - 5.5V	Commercial	40	S028	Stick
T83C5101xxx-TISCV	16K ROM	5V	Commercial	66	S028	Stick
T83C5101xxx-TISIL	16K ROM	2.7 - 5.5V	Industrial	40	S028	Stick
T83C5101xxx-TIRCL	16K ROM	2.7 - 5.5V	Commercial	40	S028	Tape & Reel
T83C5101xxx-TIRCV	16K ROM	5V	Commercial	66	S028	Tape & Reel
T83C5101xxx-TIRIL	16K ROM	2.7 - 5.5V	Industrial	40	S028	Tape & Reel
T83C5101xxx-ICUCL	16K ROM	2.7 - 5.5V	Commercial	40	SSOP24	Stick & Dry Pack
T83C5101xxx-ICUCV	16K ROM	5V	Commercial	66	SSOP24	Stick & Dry Pack
T83C5101xxx-ICUIL	16K ROM	2.7 - 5.5V	Industrial	40	SSOP24	Stick & Dry Pack
T83C5101xxx-ICFCL	16K ROM	2.7 - 5.5V	Commercial	40	SSOP24	Tape & Reel & Dry Pack
T83C5101xxx-ICFCV	16K ROM	5V	Commercial	66	SSOP24	Tape & Reel & Dry Pack
T83C5101xxx-ICFIL	16K ROM	2.7 - 5.5V	Industrial	40	SSOP24	Tape & Reel & Dry Pack
T83C5102xxx-3ZSCL	8K ROM	2.7 - 5.5V	Commercial	40	DIL24	Stick
T83C5102xxx-3ZSCV	8K ROM	5V	Commercial	66	DIL24	Stick



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Table 34. Possible Order Entries (Continued)

Part Number	Memory Size	Supply Voltage	Temperature Range	Speed (MHz)	Package	Packing
T83C5102xxx-3ZSIL	8K ROM	2.7 - 5.5V	Industrial	40	DIL24	Stick
T83C5102xxx-TDSCL	8K ROM	2.7 - 5.5V	Commercial	40	S024	Stick
T83C5102xxx-TDSCV	8K ROM	5V	Commercial	66	S024	Stick
T83C5102xxx-TDSIL	8K ROM	2.7 - 5.5V	Industrial	40	S024	Stick
T83C5102xxx-TDRCL	8K ROM	2.7 - 5.5V	Commercial	40	S024	Tape & Reel
T83C5102xxx-TDRCV	8K ROM	5V	Commercial	66	S024	Tape & Reel
T83C5102xxx-TDRIL	8K ROM	2.7 - 5.5V	Industrial	40	S024	Tape & Reel
T83C5102xxx-TISCL	8K ROM	2.7 - 5.5V	Commercial	40	S028	Stick
T83C5102xxx-TISCV	8K ROM	5V	Commercial	66	S028	Stick
T83C5102xxx-TISIL	8K ROM	2.7 - 5.5V	Industrial	40	S028	Stick
T83C5102xxx-TIRCL	8K ROM	2.7 - 5.5V	Commercial	40	S028	Tape & Reel
T83C5102xxx-TIRCV	8K ROM	5V	Commercial	66	S028	Tape & Reel
T83C5102xxx-TIRIL	8K ROM	2.7 - 5.5V	Industrial	40	S028	Tape & Reel
T83C5102xxx-ICUCL	8K ROM	2.7 - 5.5V	Commercial	40	SSOP24	Stick & Dry Pack
T83C5102xxx-ICUCV	8K ROM	5V	Commercial	66	SSOP24	Stick & Dry Pack
T83C5102xxx-ICUIL	8K ROM	2.7 - 5.5V	Industrial	40	SSOP24	Stick & Dry Pack
T83C5102xxx-ICFCL	8K ROM	2.7 - 5.5V	Commercial	40	SSOP24	Tape & Reel & Dry Pack
T83C5102xxx-ICFCV	8K ROM	5V	Commercial	66	SSOP24	Tape & Reel & Dry Pack
T83C5102xxx-ICFIL	8K ROM	2.7 - 5.5V	Industrial	40	SSOP24	Tape & Reel & Dry Pack
T87C5101xxx-3ZSCL	16K OTP ROM	2.7 - 5.5V	Commercial	40	DIL24	Stick
T87C5101xxx-3ZSCV	16K OTP ROM	5V	Commercial	66	DIL24	Stick
T87C5101xxx-3ZSIL	16K OTP ROM	2.7 - 5.5V	Industrial	40	DIL24	Stick
T87C5101xxx-TDSCL	16K OTP ROM	2.7 - 5.5V	Commercial	40	S024	Stick
T87C5101xxx-TDSCV	16K OTP ROM	5V	Commercial	66	S024	Stick
T87C5101xxx-TDSIL	16K OTP ROM	2.7 - 5.5V	Industrial	40	S024	Stick
T87C5101-TDRCL	16K OTP ROM	2.7 - 5.5V	Commercial	40	S024	Tape & Reel
T87C5101-TDRCV	16K OTP ROM	5V	Commercial	66	S024	Tape & Reel
T87C5101-TDRIL	16K OTP ROM	2.7 - 5.5V	Industrial	40	S024	Tape & Reel
T87C5101-TISCL	16K OTP ROM	2.7 - 5.5V	Commercial	40	S028	Stick
T87C5101-TISCV	16K OTP ROM	5V	Commercial	66	S028	Stick
T87C5101-TISIL	16K OTP ROM	2.7 - 5.5V	Industrial	40	S028	Stick

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Part Number	Memory Size	Supply Voltage	Temperature Range	Speed (MHz)	Package	Packing
T87C5101-TIRCL	16K OTP ROM	2.7 - 5.5V	Commercial	40	S028	Tape & Reel
T87C5101-TIRCV	16K OTP ROM	5V	Commercial	66	S028	Tape & Reel
T87C5101-TIRIL	16K OTP ROM	2.7 - 5.5V	Industrial	40	S028	Tape & Reel
T87C5101-ICUCL	16K OTP ROM	2.7 - 5.5V	Commercial	40	SSOP24	Stick & Dry Pack
T87C5101-ICUCV	16K OTP ROM	5V	Commercial	66	SSOP24	Stick & Dry Pack
T87C5101-ICUIL	16K OTP ROM	2.7 - 5.5V	Industrial	40	SSOP24	Stick & Dry Pack
T87C5101-ICFCL	16K OTP ROM	2.7 - 5.5V	Commercial	40	SSOP24	Tape & Reel & Dry Pack
T87C5101-ICFCV	16K OTP ROM	5V	Commercial	66	SSOP24	Tape & Reel & Dry Pack
T87C5101-ICFIL	16K OTP ROM	2.7 - 5.5V	Industrial	40	SSOP24	Tape & Reel & Dry Pack

Table 34. Possible Order Entries (Continued)

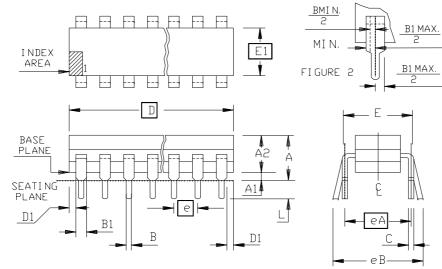
Note: For SSOP24 and S028 Packages, check with Atmel for availability.



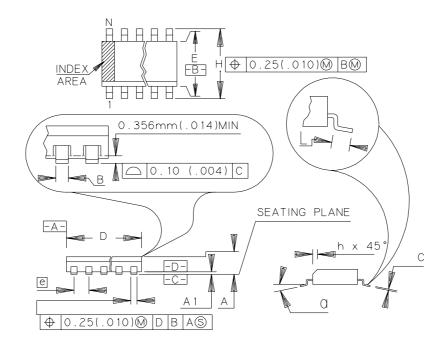


Package Drawings

DIL24



		MM .	ΙN	СН
Α	-	5. 33	-	. 21 0
A1	0.39	-	. 015	-
A2	2. 92	4. 95	. 115	. 195
В	0.36	-	. 014	_
B1	1.14	1.78	.045	. 070
С	0.20	0.38	. 008	. 015
D	28, 60	32.30	1.125	1.275
E	7.62	8. 25	. 300	. 325
E1	6.10	7.11	. 240	. 280
e	2.54	B. S. C	. 100	B. S. C
еА	7.62	B. S. C	. 300	B. S. C
еB	-	10.92	-	. 430
L	2. 92	4.06	. 115	. 160
D1	0.13	-	.005	-
PI	<g std<="" td=""><td>02</td><td></td><td></td></g>	02		



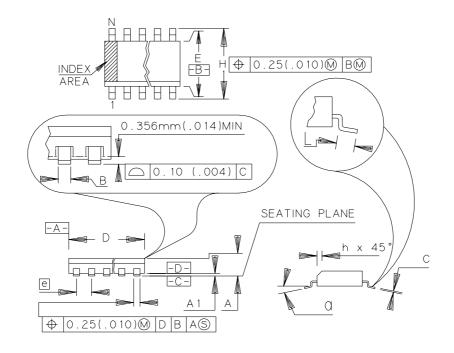
	М	M	ΙN	СН
A	2.35	2.65	. 093	. 104
A1	0.10	0.30	. 004	. 012
В	0.35	0.49	. 014	. 019
С	0.23	0.32	. 009	. 013
D	15.20	15.60	. 599	. 61 4
E	7.40	7.60	. 291	. 299
e	1.27	BSC	. 050	BSC
н	10.00	10.65	. 394	. 419
h	0.25	0.75	. 010	. 029
L	0.40	1.27	. 016	.050
N		24		24
۵		0°		8.



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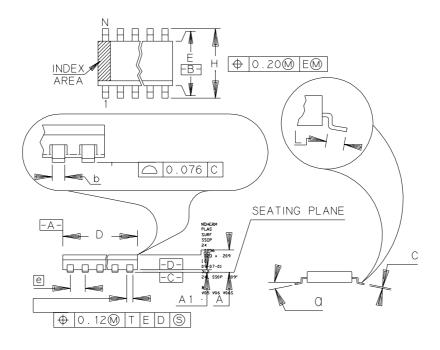


SO28



	ММ		I NCH	
A	2.35	2.65	. 093	. 104
A1	0.10	0.30	. 004	. 012
В	0.35	0.49	. 014	. 019
С	0.23	0.32	. 009	. 013
D	17.70	18.10	. 697	. 713
E	7.40	7.60	. 291	. 299
e	1.27	BSC	. 050	BSC
н	10.00	10.65	. 394	. 419
h	0.25	0.75	. 010	. 029
L	0.40	1.27	. 016	.050
N	28		28	
۵	0 °		8°	

SSOP24



	ММ		I NCH	
A	1.73	1.99	. 068	.078
A1	0.05	0.21	. 002	. 008
b	0.25	0.38	. 010	.015
С	0.09	0.20	. 004	. 008
D	8.07	8.33	. 31 8	. 328
E	5.20	5.38	. 205	. 21 2
e	0.65	BSC	. 0256	BSC
н	7.65	7.90	. 301	. 31.1
L	0.63	0.95	. 025	.037
N	24		24	
۵	0°	8°	0°	8°





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